

IN THE CLAIMS

Please replace the following claims with the new replacement claims.

- a¹
1. (Amended) A semiconductor wafer grinding method, comprising:
grinding a semiconductor wafer by fixed abrasive grains; and
continuously grinding the semiconductor wafer by free abrasive grains wherein
grinding occurs on the same grinding axis.

- a²
3. (Amended) The semiconductor wafer grinding method according to claim 1,
wherein grinding includes both sides of a semiconductor wafer or grinding of a chamfered
portion.

Please ADD the following NEW claim.

- a³
4. (New) The semiconductor wafer grinding method according to claim 2, wherein
grinding includes both sides of a semiconductor wafer or grinding of a chamfered portion.